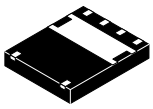
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

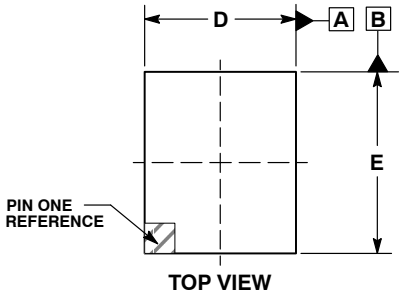
ON Semiconductor®



SCALE 2:1

DFN6 5x6, 1.27P
CASE 506DV
ISSUE O

DATE 12 OCT 2016

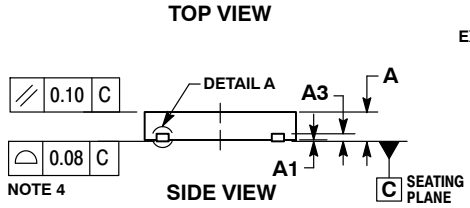


TOP VIEW

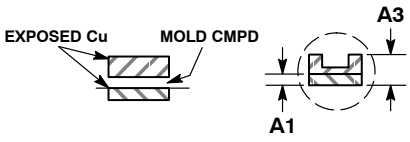
DETAIL A
ALTERNATE TERMINAL CONSTRUCTIONS

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.20 AND 0.25 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. FOR DEVICE OPN CONTAINING W OPTION, DETAIL B ALTERNATE B–1 AND DETAIL A ALTERNATE A–1 CONSTRUCTIONS ARE NOT APPLICABLE.

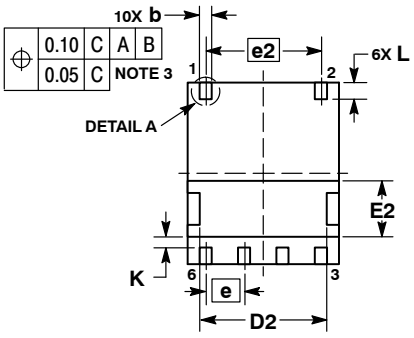
	MILLIMETERS		
DIM	MIN	NOM	MAX
A	0.80	0.90	1.00
A1	---	---	0.05
A3		0.20 REF	
b	0.30	0.40	0.50
D	4.90	5.00	5.10
D2	4.10	4.20	4.30
E	5.90	6.00	6.10
E2	1.75	1.85	1.95
e		1.27 BSC	
e2		3.81 BSC	
K	0.25	---	---
L	0.45	0.55	0.65



SIDE VIEW

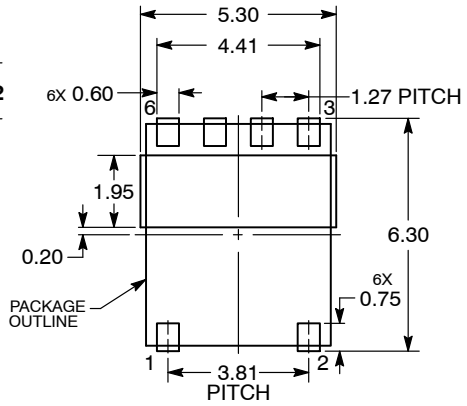


DETAIL B
ALTERNATE CONSTRUCTIONS



BOTTOM VIEW

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*

A = Assembly Location
LL = Wafer Lot
YY = Year
WW = Work Week
▪ = Pb–Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot " ▪", may or may not be present.

DOCUMENT NUMBER:	98AON16235G	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	DFN6 5X6, 1.27P		PAGE 1 OF 1